01-16-04 1762

Express Mail No. EV 346 810 351 US.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Claire RICHTARCH

Application No: 10/671,812

Filing Date: September 25, 2003

For: METHOD OF PREPARING A SURFACE OF A SEMICONDUCTOR WAFER TO MAKE IT EPIREADY

Confirmation No.6886

Group Art Unit: 1762

Examiner:

Atty. Docket No.: 4717-11300

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Pursuant to applicants' duty of disclosure under 37 C.F.R. 1.56, enclosed is a PTO form 1449 which lists (3) cited references for the Examiner's review and consideration. It is respectfully requested that these references be made of record in this application by the Examiner's completion and return of the PTO Form 1449.

No fee or certification is believed to be due for this submission since the filing of this statement is being submitted prior to the issuance of the first office action for this application. Should any fees be required, however, please charge such fees to **Winston & Strawn** Deposit Account No. 50-1814.

Respectfully submitted,

Date: 1/14/04

Allan A. Fanucci (Reg. No. 30,256)

WINSTON & STRAWN LLP
CUSTOMER NO. 28765

(212) 294-3311

Enclosures

LIST OF REFERENCES CITED BY APPLICANT Form PTO-1449 *(Use several sheets if necessary)*	ATTY. DOCKET NO.: 4717-11300	APPLICATION NO.: 10/671,812
	APPLICANT: Claire RICHTARCH	
	FILING DATE: September 25, 2003	GROUP: 1762

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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	CITE NO.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						

FOREIGN PATENT DOCUMENTS

AE

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES	TRANSLATION NO
	AE	FR 02-09869	8/2002	France			X	
	AF							
	AG							

OTHER REFERENCES (*Including Author, Title, Date, Pertinent Pages, Etc.*)

	AH	A. J. Auberton-Hervé et al., "Why Can SMART-CUT® Change the Future of Microelectronics?", International Journal of High Speed Electronics and Systems, Vol. 10, no. 1, 2000, pp 131-146.
	AI	"Thermal and Dopant Processes", Chapter 4, Advanced Semiconductor Fabrication Handbook, ICE, 1998
	AJ	
	AK	

EXAMINER	

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with **MPEP 609**. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

AM